

APPLICATION DATA SHEET

Electronic Version v14

Stylesheet Version v14.0

Title of Invention

[HEAT SINK FOR CHIP PACKAGE AND BONDING METHOD THEREOF]

Application Type : regular, utility

Attorney Docket Number : 10233-US-PA

Correspondence address:

Customer Number: 31561



Priority Data:

Doc.No: 91137108; Country -TW ; Date: 2002-12-24 us-priority-claimed

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